Claims

1. A polishing apparatus comprising: a turntable which has a polishing pad attached thereto; a polishing head configured to hold a wafer; a tank configured to store a polishing agent; a polishing agent supply mechanism which supplies the polishing agent stored in the tank to the polishing pad; a waste liquid receiver which collects the polishing agent flowing down from an upper side of the turntable; and a circulation mechanism which is connected to the waste liquid receiver and supplies the polishing agent collected by the waste liquid receiver to the tank, the polishing agent being supplied to the polishing pad from the tank by the polishing agent supply mechanism, the used polishing agent which flows down from the upper side of the turntable being collected by the waste liquid receiver, a surface of the wafer held by the polishing head being rubbed against the polishing pad so that it is polished while supplying the collected polishing agent to the tank to circulate the polishing agent,

wherein the waste liquid receiver is fixed to the turntable,

wherein the waste liquid receiver is formed of a bottom plate and a side plate, and the side plate is removable.

2. The polishing apparatus according to claim 1,

wherein the waste liquid receiver is formed into a ring-like shape which surrounds a side surface of the turntable.

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